

C1206C821JBGACTU

Aliases (C1206C821JBGAC7800) SMD Comm COG HV, Ceramic, 820 pF, 5%, 630 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1206, 1.5 mm



| General Information | |
|--------------------------|---|
| Series | SMD Comm COG HV |
| Style | SMD Chip |
| Description | SMD, MLCC, Ultra-Stable, Low Loss, Class I |
| Features | Ultra-Stable, Low Loss, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 30 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|---------------------------|
| Capacitance | 820 pF |
| Measurement Condition | 1 MHz 1.0Vrms |
| Tolerance | 5% |
| Voltage DC | 630 VDC |
| Dielectric Withstanding Voltage | 945 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |

 Chip Size
 1206

 L
 3.2mm +/-0.2mm

 W
 1.6mm +/-0.2mm

 T
 1.2mm +/-0.15mm

 S
 1.5mm MIN

 B
 0.5mm +/-0.25mm

Click here for the 3D model.

Packaging SpecificationsPackagingT&R, 180mm, Plastic TapePackaging Quantity2500

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Dimensions